

Features

- 3535 UVB LED
- ROHS and REACH Compliant
- MSL 3 qualified according to J-STD 020

Description

The IN-C35PPBTGUB is a mid-power UVB LED. It is a SMD type LED which can be used in various applications.

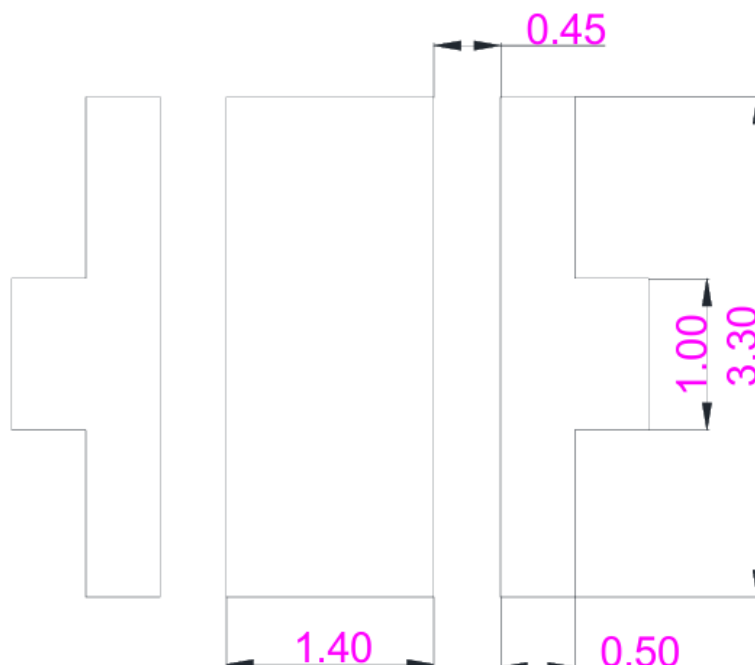
Applications

- Medical applications
- Biological applications
- Industrial facility applications

Recommended Solder Pattern

(Suggest Stencil $t=0.12$ mm)

Figure 1. IN-C35PPBTGUB Recommended Solder Pattern



Note:

All dimensions are in millimeters.
Tolerance is ± 0.1 mm unless other specified.

Package Dimensions

(All dimensions are in mm, tolerance is $\pm 0.1\text{mm}$)

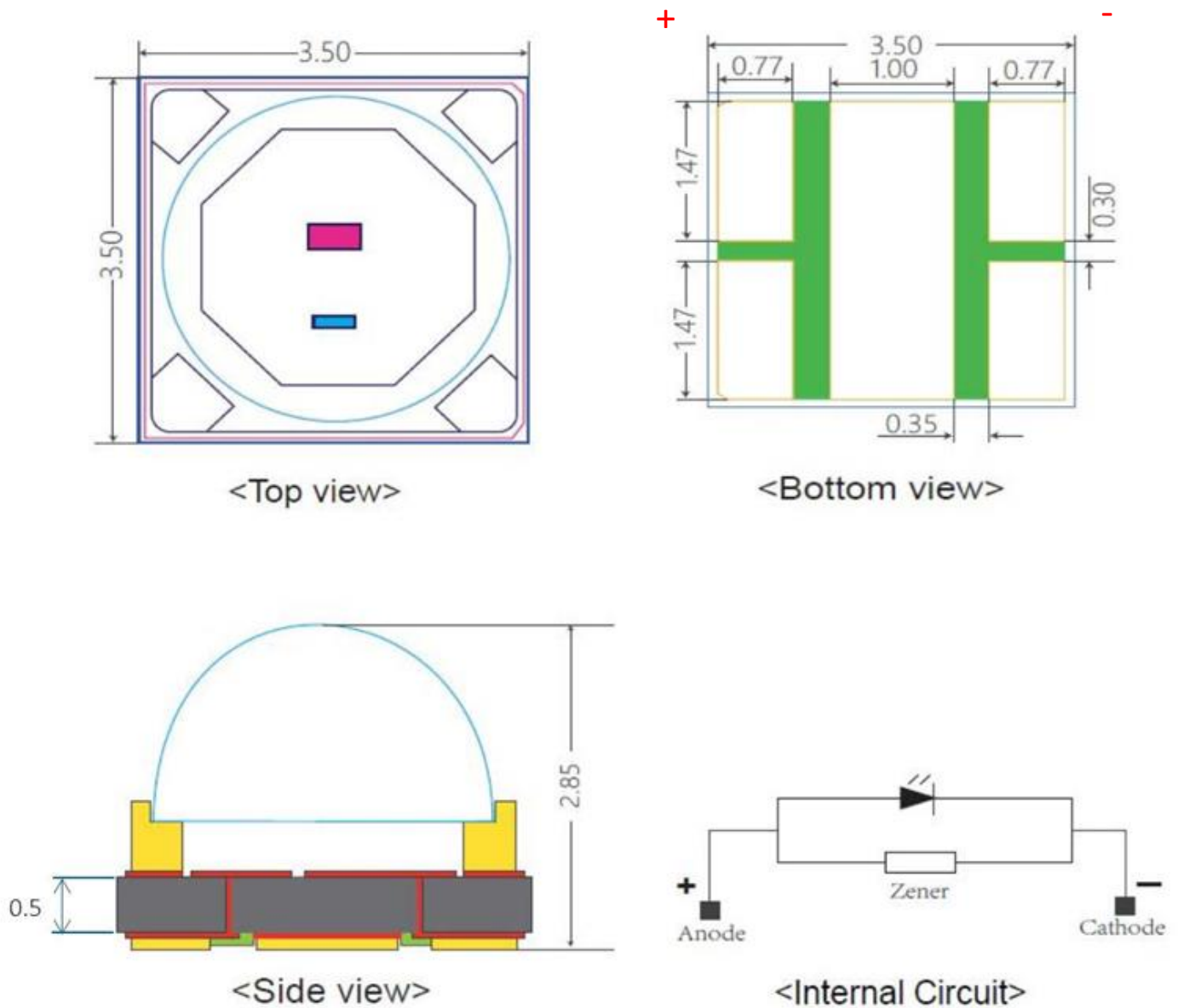


Figure 2. IN-C35PPBTGUB Package Dimension

Absolute Maximum Rating at 25°C

Characteristics	Symbol	Min.	Typical	Max.	Unit
DC Forward Current	IF		150		mA
Power Dissipation	Pd		1000		mW
Junction Temperature	Tj			60	°C
Reverse Voltage	VR		5.0		V
Storage Temperature Range	Tstg	-40	–	100	°C
Operating Temperature	Topr	-10	–	60	°C
Soldering Temperature	Tsol		260		°C

Notes:

1. Operating the LED beyond the listed maximum ratings may affect device reliability and cause permanent damage.
2. The LEDs are not designed to be driven in reverse bias.

Electronic-Optical Characteristics (Ambient Temp: 25°C)

Characteristics	Symbol	Min.	Typical	Max.	Unit
DC Forward Current	IF		100		mA
Forward Voltage	VF	5.0	6.0	7.0	V
Radiant Flux	Φe		20		mW
Peak Wavelength	λp	300	308	315	nm
Thermal Resistance	RTHJ-S		12.5		°C/W
Spectrum Half Width	Δλ		11		nm
Viewing Angle	2θ1/2		60		Deg
Reverse Current	Ir			10	μA

Note:

1. Forward Voltage (Vf): ±0.1V
2. Peak Wavelength(λp): ±3.0nm
3. Radiant Flux(Φe): ±10%
4. Viewing angle(2θ1/2) ± 10°

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection

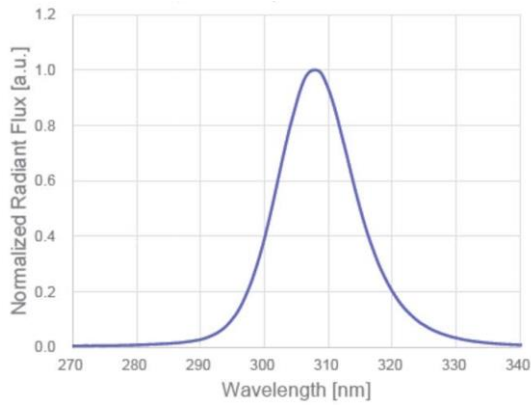


The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

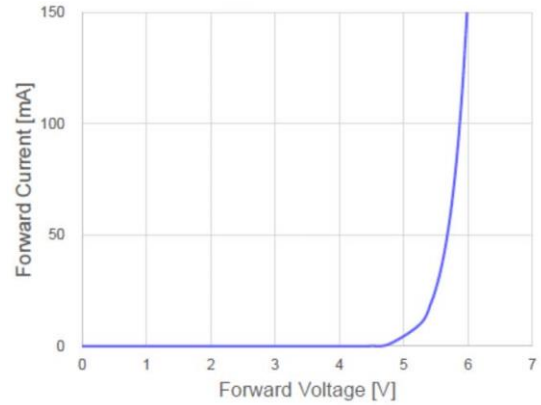
Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

Typical Characteristics Curves

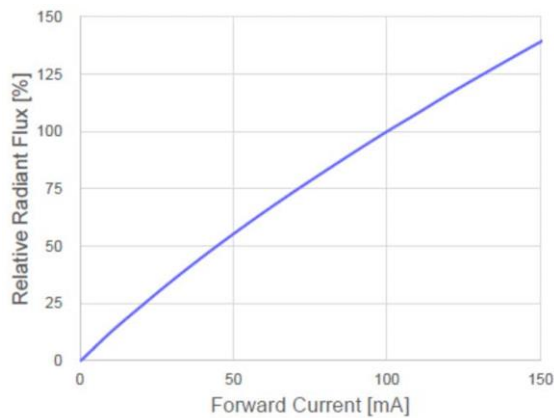
Relative Spectral Power Distribution ($I_F=100\text{mA}$)



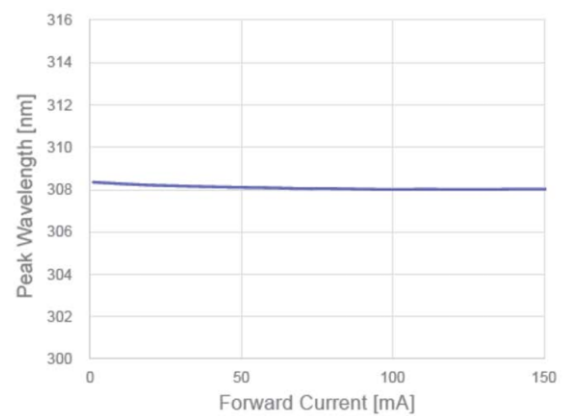
Forward Current vs. Forward Voltage ($T_a=25^\circ\text{C}$)



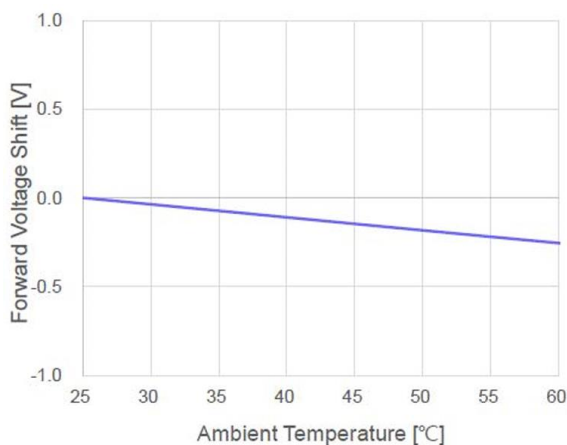
Relative Radiant Flux vs. Forward Current ($T_a=25^\circ\text{C}$)



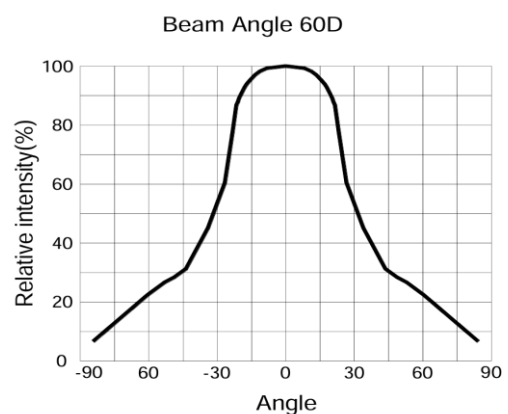
Peak wavelength Forward Current ($T_a=25^\circ\text{C}$)



Ambient Temperature vs Forward Voltage Shift



Radiation Characteristics



Notes:

Viewing angle $(2\theta_{1/2}) \pm 10^\circ$

Ordering Information

Peak Wavelength Range	Beam Angle	Forward Voltage(V)		Part Number
UB: 300~315nm	60°	Min	Max	IN-C35PPBTGUB
		5.0	7.0	

Label Specifications

Inolux P/N:

I	N	-	C	3	5	PPB	T	G	UB	-	X	X	X	X
Inolux SMD			Material	Package		Variation	Orientation	Current	Color		Customized Stamp-off			
			C = Ceramic Type	35PPB = 3.5 x 3.5, 60 Deg.			T = Top Mount	G=100mA	UB = 300- 315nm					

Lot No.:

Z	2	0	1	7	01	24	001
Internal Tracker	Year (2017, 2018,)				Month	Date	Serial

Forward Voltage Binning

Voltage unit: V@100mA			
Peak Wavelength	Bin Code	Min	Max
UB 300nm-315nm	A	5.0	6.0
	B	6.0	7.0

Notes:

1. Binning current is 100 mA

Radiant flux (Power) binning

Bin Code (100mA)	Min. Po (mW)	Typ. Po (mW)
P1	10	20

Notes:

1. Binning current is 100mA

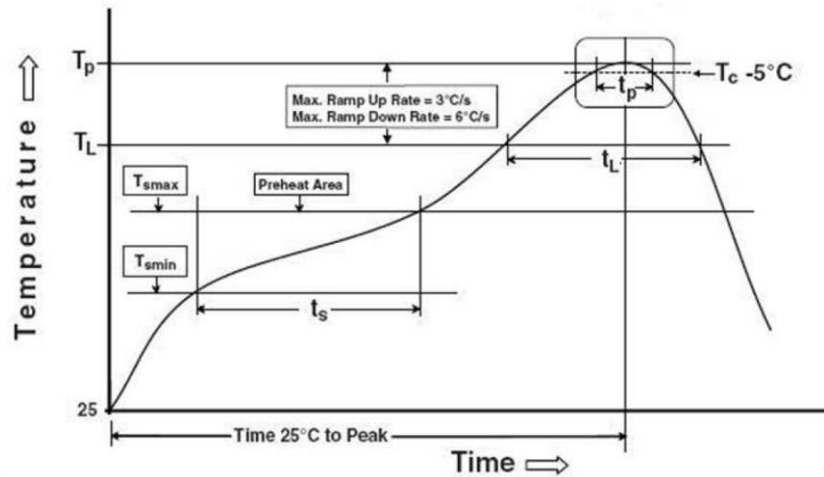
Peak wavelength binning reference table

Bin code (100mA)	Min. Wp (nm)	Max. Wp (nm)
UVB	300.0	315.0

Notes:

1. Peak-wavelength (Wp) tolerance: $\pm 3.0\text{nm}$
2. Testing Current 100mA

Reflow Soldering



Profile Feature	Lead Free Assembly
Average Ramp-Up Rate (T_L to T_P)	3°C / second max
Preheat Temperature Min (T_{smin})	150°C
Preheat Temperature Max (T_{smax})	200°C
Preheat Time (t_s)	60 – 120 seconds
Time Maintained Above Temperature (T_L)	217°C
Time Maintained Above Time (t_L)	60 – 150 seconds
Peak / Classification Temperature (T_P)	260°C *
Time Within 5°C of Actual Peak Temperature (t_p)	10~30 seconds
Ramp – Down Rate (T_P to T_L)	6°C / second max
Time 25°C to Peak Temperature	8 minutes max

The recommended peak temperature is 245°C. The maximum soldering temperature should be controlled under 260°C

Soldering Iron

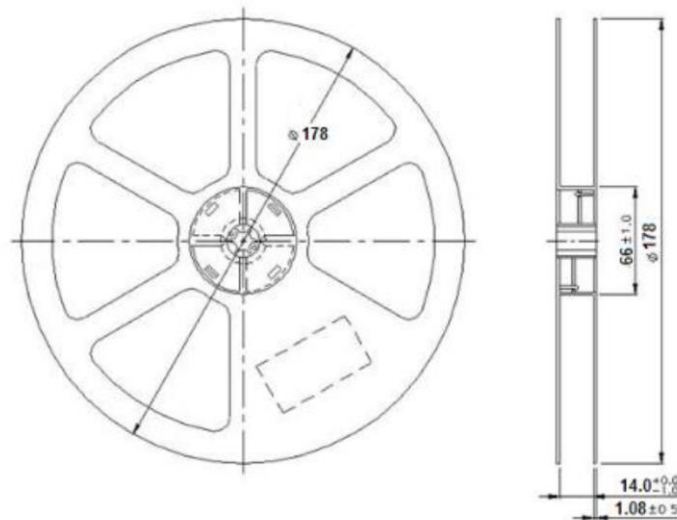
Basic Spec is ≤ 4 sec. when 260°C (+10°C $\rightarrow$ -1 second). Power dissipation of Iron should be less than 15W. Surface temperature should be under 230°C

Rework

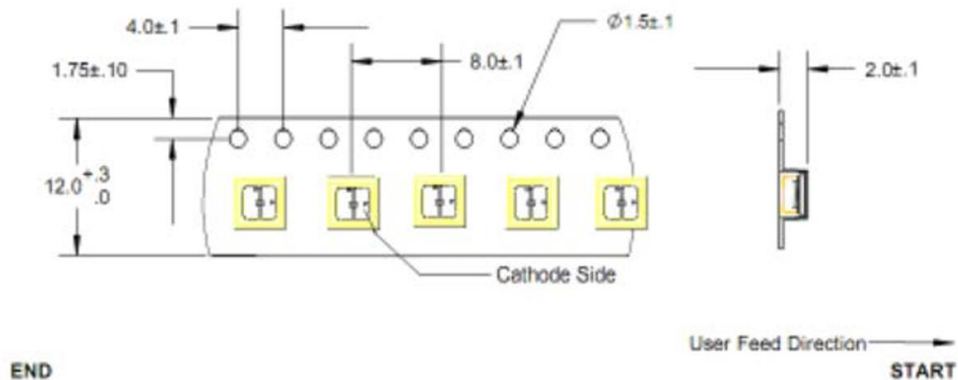
Rework should be completed within 4 second under 245°C

Packing

Reel



Tape



Notes:

1. Each Reel (minimum number of pieces is 100 and maximum is 500 (60D) is packed in a moisture-proof bag along with 2 packs of desiccant and a humidity indicator card.
2. Part No., Lot No., quantity should be indicated on the label of the moisture-proof bag and the cardboard box.

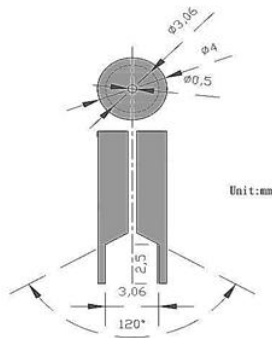
Precautions

1. Recommendation for using LEDs

- 1.1 The lens of LEDs should not be exposed to dust or debris. Excessive dust and debris may cause a drastic decrease in the luminosity.
- 1.2 Avoid mechanical stress on LED lens.
- 1.3 Do not touch the LED lens surface. It would affect the optical performance of the LED due to the LED lens' damage.
- 1.4 Pick & place tools are recommended for the remove of LEDs from the factory tape & reel packaging

2. Pick & place nozzle

The pickup tool was recommended and shown as below



3. Lens handling

Please follow the guideline to pick LEDs

- 3.1 Use tweezers to pick LEDs
- 3.2 Do not touch the lens by using tweezers
- 3.3 Do not touch lens with fingers
- 3.4 Do not apply more than 4N of lens (400g) directly onto the lens

4. Lens cleaning

In the case which a small amount of dirt and dust particles remain on the lens surface, a suitable cleaning solution can be applied.

- 4.1 Try a gentle wiping with dust-free cloth
- 4.2 If needed, use dust-free cloth and isopropyl alcohol to gently clean the dirt from the lens surface.
- 4.3 Do not use other solvents as they may directly react with the LED assembly
- 4.4 Do not use ultrasonic cleaning which will damage the LEDs

Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	06-04-2024

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